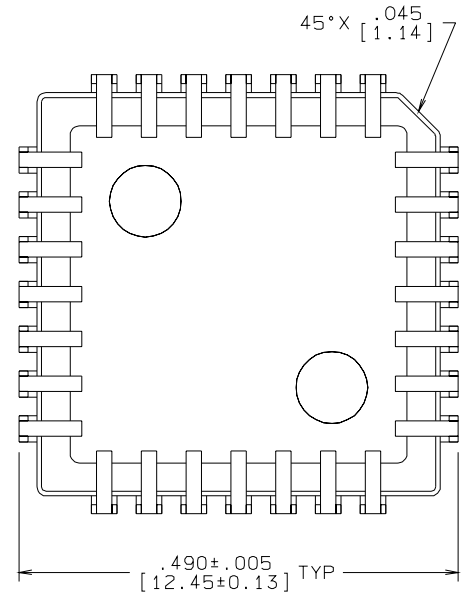
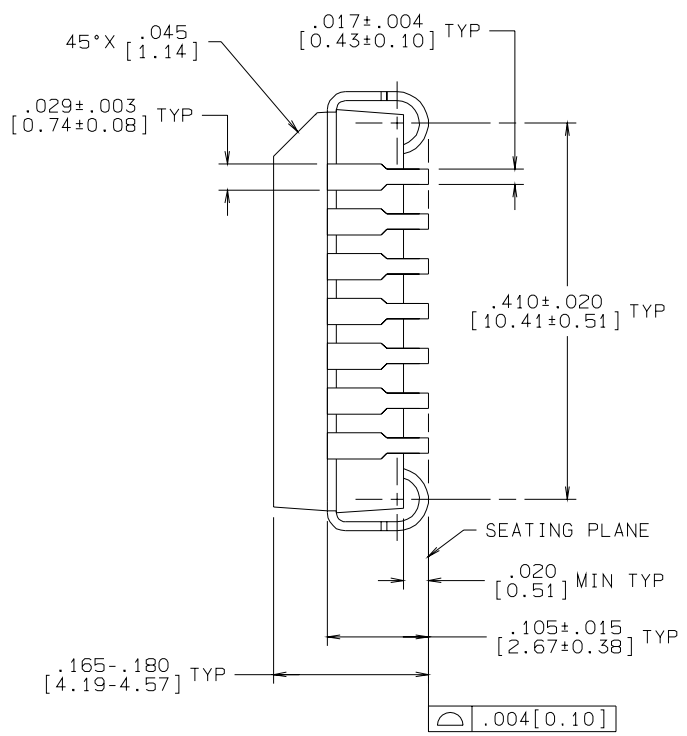
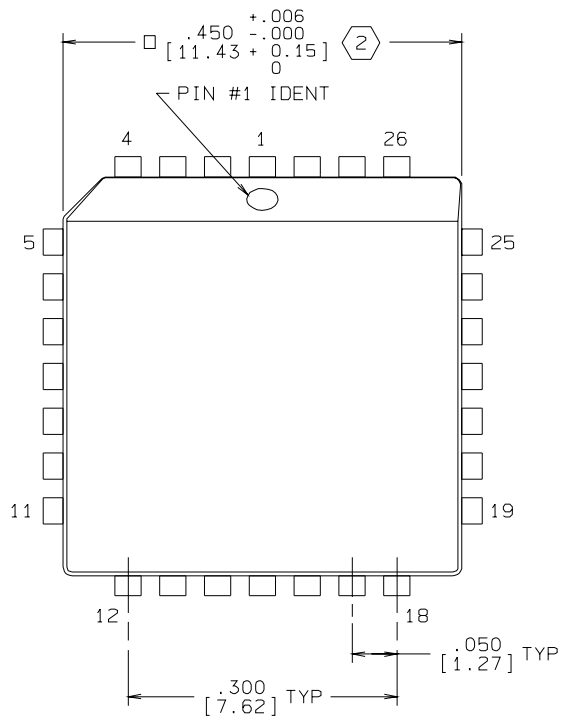


R E V I S I O N S				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
H	REVISE & REDRAW	09215	07/06/92	TL/SL
J	REVISE NOTES 1 & 3; ADD CHAMFER DIM TO BOT VIEW; TOP VIEW: .450 WAS .448, 11.43 WAS 11.38	09327	09/23/92	TL/SL
K	ADD COPLANARITY & SEATING PLANE; CONVERT LIMIT DIM'S TO NOM±TOL.; REVISE TITLE.	10035	12/02/93	MS/



CONTROLLING DIMENSION: INCH

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
200 MICROINCHES / 5.08 MICROMETERS MINIMUM SOLDER THICKNESS PER SIDE ON COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION .010 IN / 0.25 mm PER SIDE.
- REFERENCE JEDEC REGISTRATION MO-047, VARIATION AB, DATED 5/90.

APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION		
DRAWN T. LEQUANG	07/06/92	2900 Semiconductor Drive, Santa Clara, CA 95052-8090		
DFTG. CHK.		PLASTIC CHIP CARRIER, SQ., .050 LD PITCH, 28 LEAD		
ENGR. CHK.		SCALE	SIZE	DRAWING NUMBER
APPROVAL		N/A	B	MKT-V28A
 PROJECTION INCH [MM]		REV	K	
		DO NOT SCALE DRAWING	SHEET	1 OF 1